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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION FOR LETTERS PATENT

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**SEMICONDUCTOR PROCESSOR SYSTEMS,
SYSTEMS CONFIGURED TO PROVIDE A
SEMICONDUCTOR WORKPIECE PROCESS
FLUID, SEMICONDUCTOR WORKPIECE
PROCESSING METHODS, METHODS OF
PREPARING SEMICONDUCTOR WORKPIECE
PROCESS FLUID, AND METHODS OF
DELIVERING SEMICONDUCTOR WORKPIECE
PROCESS FLUID TO A SEMICONDUCTOR
PROCESSOR**

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EV085431865

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1 SEMICONDUCTOR PROCESSOR SYSTEMS, SYSTEMS
2 CONFIGURED TO PROVIDE A SEMICONDUCTOR WORKPIECE
3 PROCESS FLUID, SEMICONDUCTOR WORKPIECE PROCESSING
4 METHODS, METHODS OF PREPARING SEMICONDUCTOR
5 WORKPIECE PROCESS FLUID, AND METHODS OF DELIVERING
6 SEMICONDUCTOR WORKPIECE PROCESS FLUID TO A
7 SEMICONDUCTOR PROCESSOR

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8 RELATED PATENT DATA

9 The present application is a continuation-in-part of Patent
10 Application Serial No. 09/324,737 which was filed on June 3, 1999 and
11 which is incorporated by reference herein.

12 TECHNICAL FIELD

13 The present invention relates to semiconductor processor systems,
14 systems configured to provide a semiconductor workpiece process fluid,
15 semiconductor workpiece processing methods, methods of preparing
16 semiconductor workpiece process fluid, and methods of delivering
17 semiconductor workpiece process fluid to a semiconductor processor.

18 BACKGROUND OF THE INVENTION

19 Numerous semiconductor processing tools are typically utilized
20 during the fabrication of semiconductor devices. One such common
21 semiconductor processor is a chemical-mechanical polishing (CMP)
22 processor. A chemical-mechanical polishing processor is typically used
23 to polish or planarize the front face or device side of a semiconductor
24 wafer. Numerous polishing steps utilizing the chemical-mechanical

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